



IN THE
UNITED STATES PATENT
AND TRADEMARK OFFICE

Application Number **09/996,802**

Filing Date **November 30, 2001**

First Named Inventor **SATO**

Group Art Unit **1712**

Examiner Name **Feely, Michael J.**

Attorney Docket Number **2922-172**

Title: **RESIN COMPOUND FOR FABRICATING INTERLAYER DIELECTRIC OF PRINTED WIRING BOARD, RESIN SHEET AND RESIN APPLIED-COPPER FOIL FOR FORMING INSULATING LAYER USING THE RESIN COMPOUND, AND COPPER-CLAD LAMINATE USING THEM**

AMENDMENT AND REQUEST FOR RECONSIDERATION

Assistant Commissioner for Patents
Washington, D.C. 20231

RECEIVED
MAY 27 2003
GROUP 1700

Dear Sir:

In response to the Office Action dated February 21, 2003, please amend the above identified U.S. patent application as follows:

IN THE CLAIMS:

Please amend claims 1 - 8, and add new claims 13-21 as shown on the following pages.

Marked-up copies of the original text of the amended claims are attached to this amendment. Material inserted is indicated by underlining (insertion) and material deleted is indicated by bracketing ([deletion]).

05/22/2003 HGUTEMA1 00000084 09996802

01 FC:1202
02 FC:1201

18.00 OP
168.00 OP